

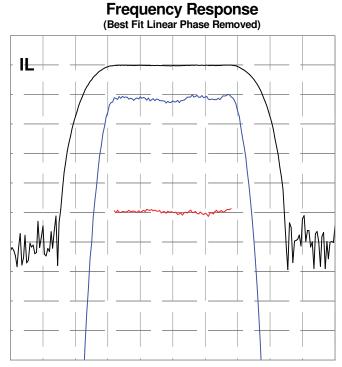
## **Specifications**

Parameter	Symbol	Min	Typical	Max	Unit
Center Frequency	Fo		70		MHz
Bandwidth	В		20		MHz
–3 dB Bandwidth	B <sub>3</sub>	23.3	23.5		MHz
–40 dB Bandwidth	B <sub>40</sub>		33.8	34	MHz
Delay	To	1.25	1.258	1.26	µsec
Insertion Loss	IL		26.4	27	dB
Amplitude Ripple			0.3	0.5	dB <sub>P-P</sub>
Phase Ripple			2.1	3	deg <sub>P-P</sub>
Rejection		50	54		dB
Spurious for $ t - T_0  > .9T_0$			-53	-48	dB
Substrate Material	128YX-LN				

### Notes

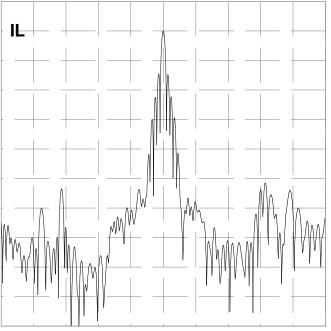
- 1. Center Frequency (F<sub>0</sub>) and Bandwidth (B) are defined, not measured.
- 2. Insertion Loss is the minimum loss for  $|f F_0| < .5B$
- 3. Ripple spec applies to the  $|f F_0| < .4B$ , and is doubled for  $.4B < |f F_0| < .5B$
- 4. Rejection spec applies to  $(B_{40} \mbox{ Spec} B/2) < |f F_0| < F_0/2$
- 5. Specifications are at 22 °C only. Unit will operate undamaged from -54 °C to 125 °C with shifts dF<sub>0</sub> =  $-x^*$  F<sub>0</sub>, dT<sub>0</sub> =  $x^*$  T<sub>0</sub>, where  $x = 75E-6^*$  (temperature -22 °C)

## **Typical Performance**



10 dB/div, 1 dB/div, 10 deg/div, 5.000 MHz/div

Impulse Response FFT(Frequency Response\*Cos(0.5\*PI\*MIN(1,MAX(0,|f-F0|\*2.0/B-1.0)))^2)

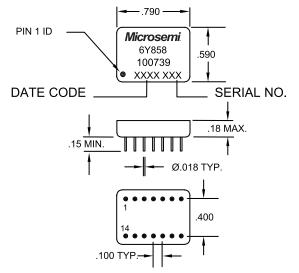


10 dB/div, 0.400 us/div

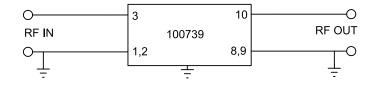


# 100739C FB70-20.5 20 MHz Bandwidth 70 MHz Bandpass Filter

## Package Outline



## Matching





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MSCC-0347-DS-01090-2.00-0717